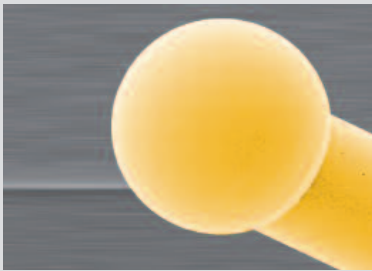
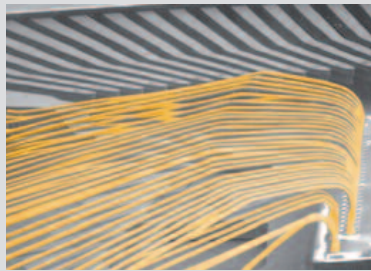


## Au HD6 Gold Bonding Wire for Fine Pitch and Low Loop



These highly doped wires of different chemical compositions are very suitable for low and long loop applications. Both wire types are comparable in their characteristics and offer outstanding material and processing properties as well as good high temperature strength.



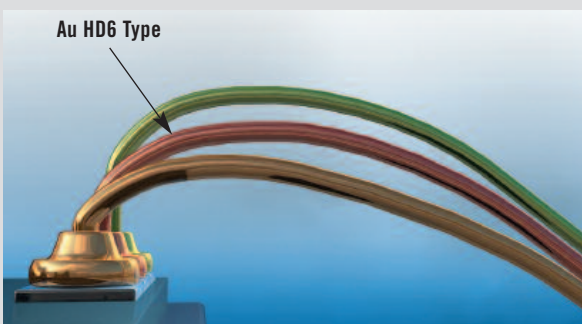
They represent an excellent bridge between doped and alloyed wires.

Areas of application

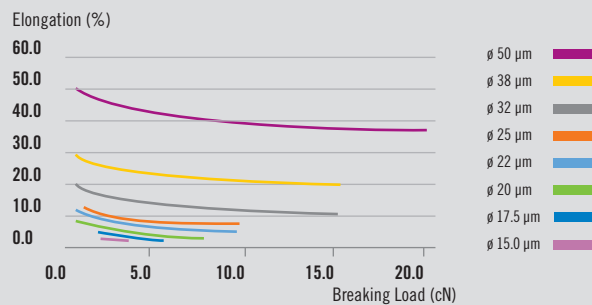
- Flat integrated circuits (BGA, MQFP, CQP, TSOP, TQFP, VSSOP, IC-cards,...)
- COB, foil frames

### Au HD6 Benefits

- Low and long loop wire type
- Soft type bonding wire of high ductility
- Exact loop guiding
- Mid strength type
- Well proven loop stiffness and thermal stability
- Suitable for all high performance bonding machines
- For normal and high speed assembling



### Breaking Load vs. Elongation



### Recommended Technical Data of Au HD6

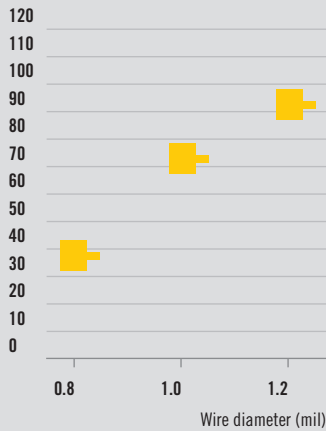
Diameter	Microns (µm)	17.5	20	23	25	30	32	38	50
	Mils	0.7	0.8	0.9	1.0	1.2	1.25	1.5	2.0
Elongation	%	2 – 5	2 – 5	2 – 8	2 – 8	2 – 8	2 – 8	3 – 8	3 – 10
Breaking Load	cN	> 4	> 5	> 7	> 9	> 13	> 14	> 19	> 34

## Characteristics of Au HD6

<b>Non-Gold Elements</b>	< 100 ppm	<b>Melting Point</b>	1063 °C
<b>Break Load @ Room Temperature at 4% EL</b>	> 11 g	<b>Density</b>	19.32 g/cm <sup>3</sup>
<b>Break Load @ 250°C / 20 sec</b>	> 10 g	<b>Heat Conductivity</b>	3.12 W/cmK
<b>Elastic Modulus</b>	> 70 GPa	<b>Electrical Resistivity</b>	2.2 μOhm-cm
<b>Heat Affected Zone (HAZ) on 50 μm ball diameter</b>	50 μm	<b>Coeff. of Linear Expansion (0 – 100°C)</b>	14.2 ppm / K
<b>Neck Strength at 37 μm ball diameter</b>	8 g	<b>Fusing Current for 25 μm, dia 10 mm length (in air)</b>	0.5 A

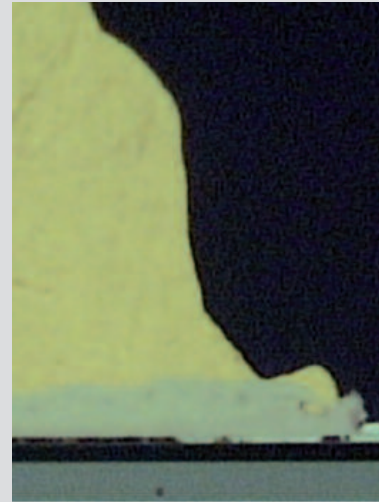
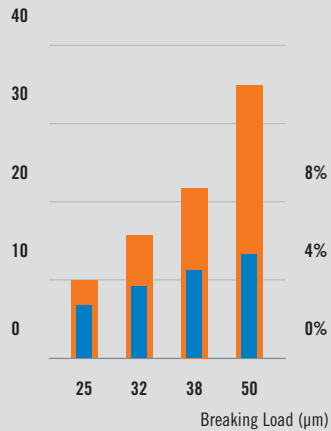
## Heat Affected Zone (HAZ)

Length of HAZ (μm)

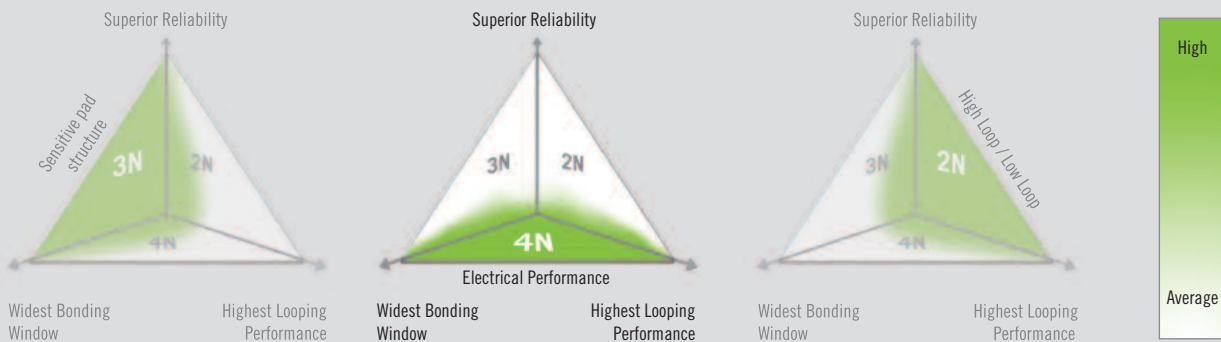


## High Temperature Strength (HTS)

Breaking Load (cN) ■ Elontaion (%)



## Gold Wire Segmentation by Properties



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